

Displacement Damage Effects in Single-Event Gate Rupture

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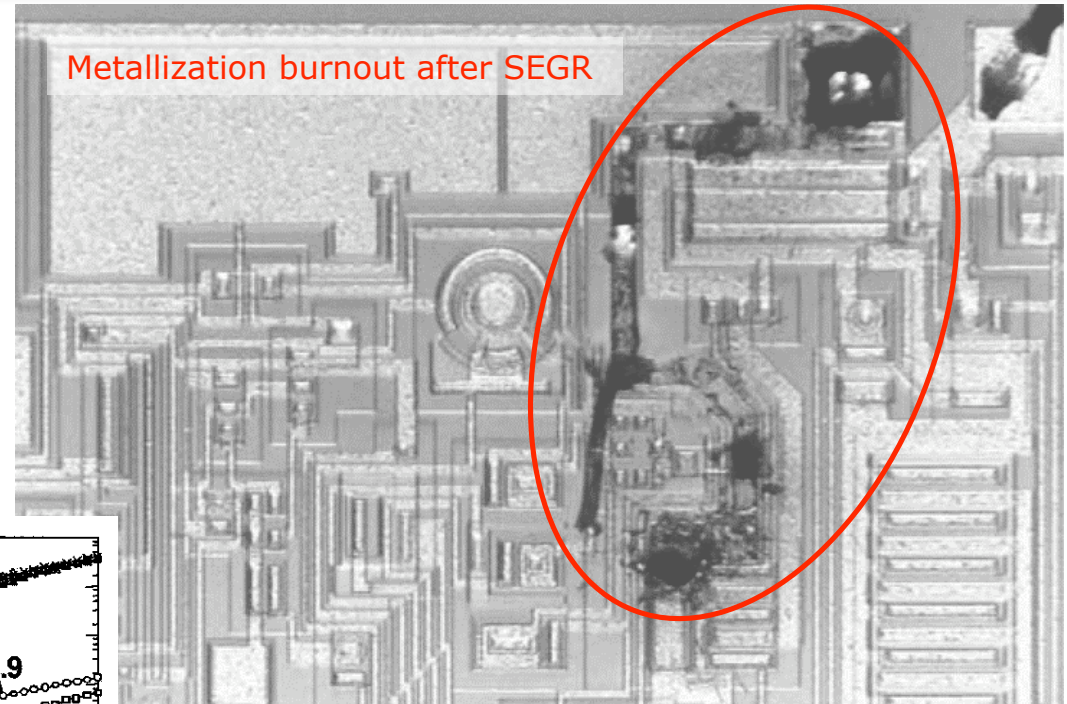


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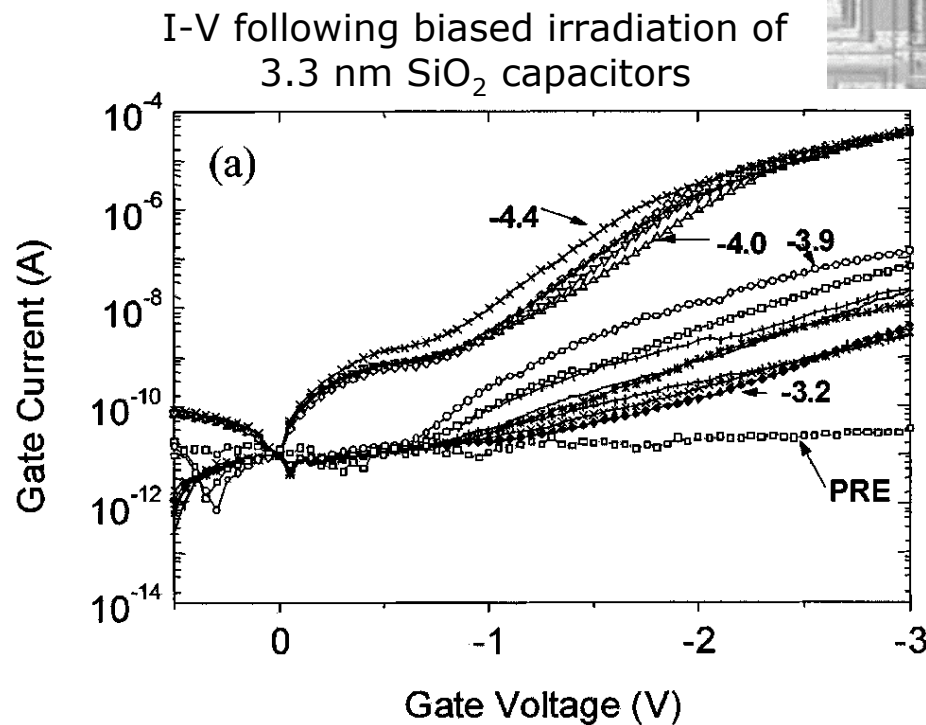


Background: Single-Event Gate Rupture

Single-ion induced dielectric failure
MOSFETs, Capacitors, FG Devices

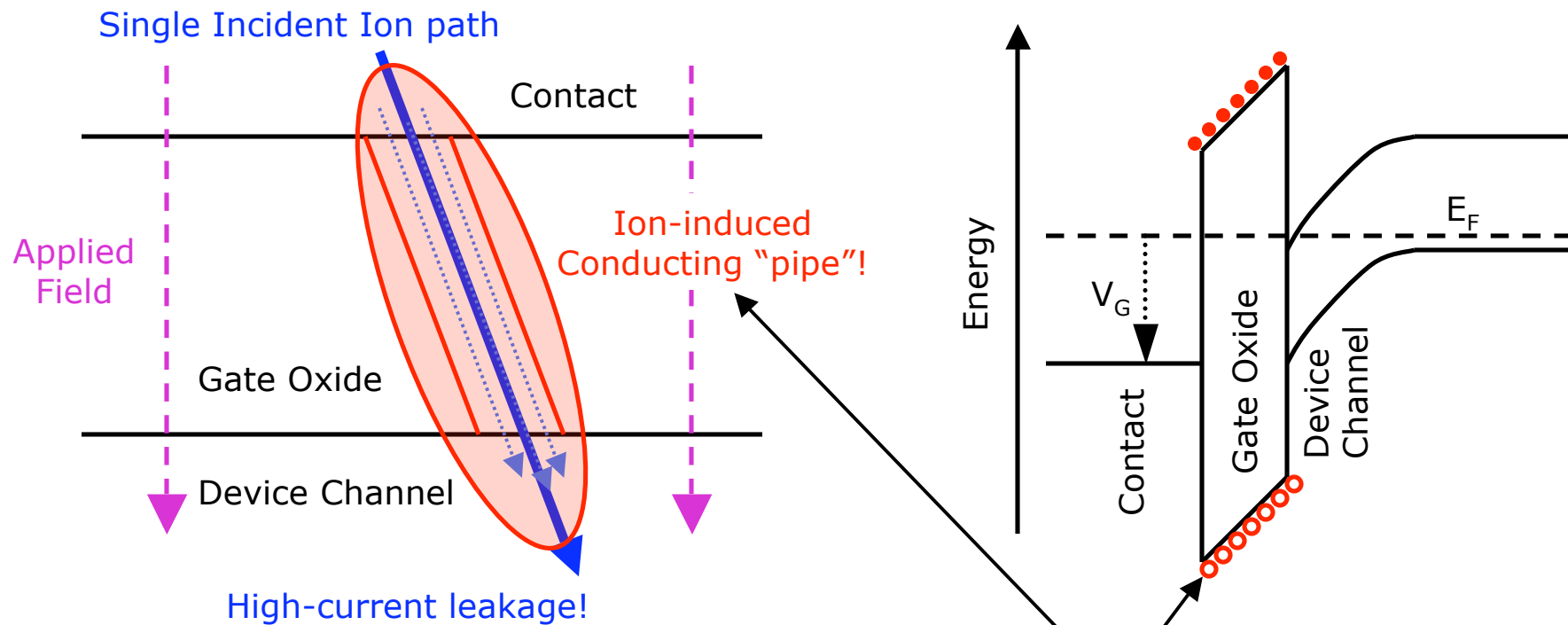


Lum, et al., IEEE TNS 51 3263 (2004)



Massengill, et al., IEEE TNS 48 1904 (2001)

Background: Single-Event Gate Rupture



⇒ Local heating/melting

⇒ Permanent damage + Device Failure

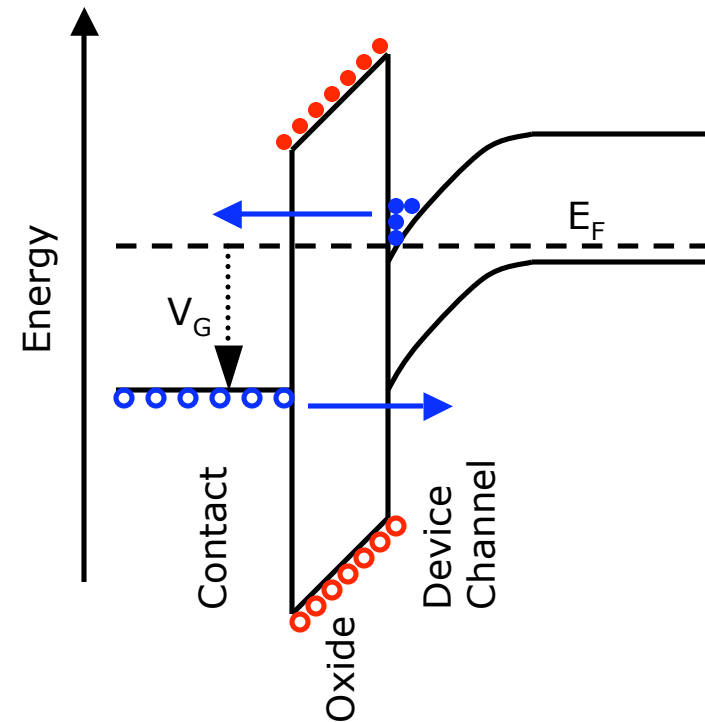
Typically associated with electronic excitations (LET)

Background: Leakage-induced Melting

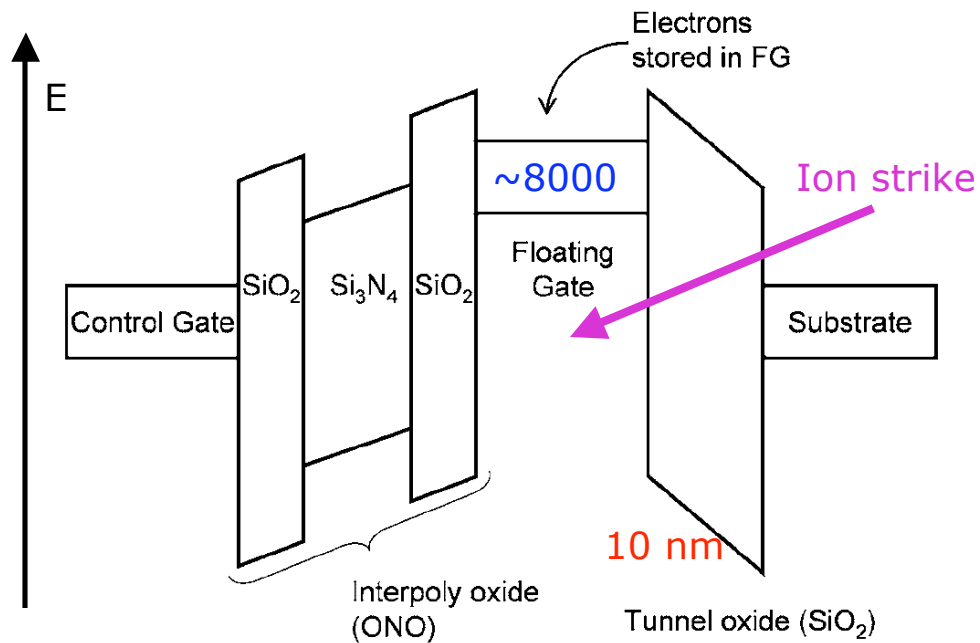
Local heating is due to motion
of ion-excited carriers...

$$\frac{1}{E_{CR}} = \frac{q\mu_1 n(V)}{J_{CR}} + \frac{q\mu_2 n(L)}{J_{CR}}$$

...AND carriers injected by
the applied field!



How does the ion strike induce carrier injection?



Ion-excited e-h pairs surviving recombination: **~80**

Effective Discharge: **~4000 e⁻**

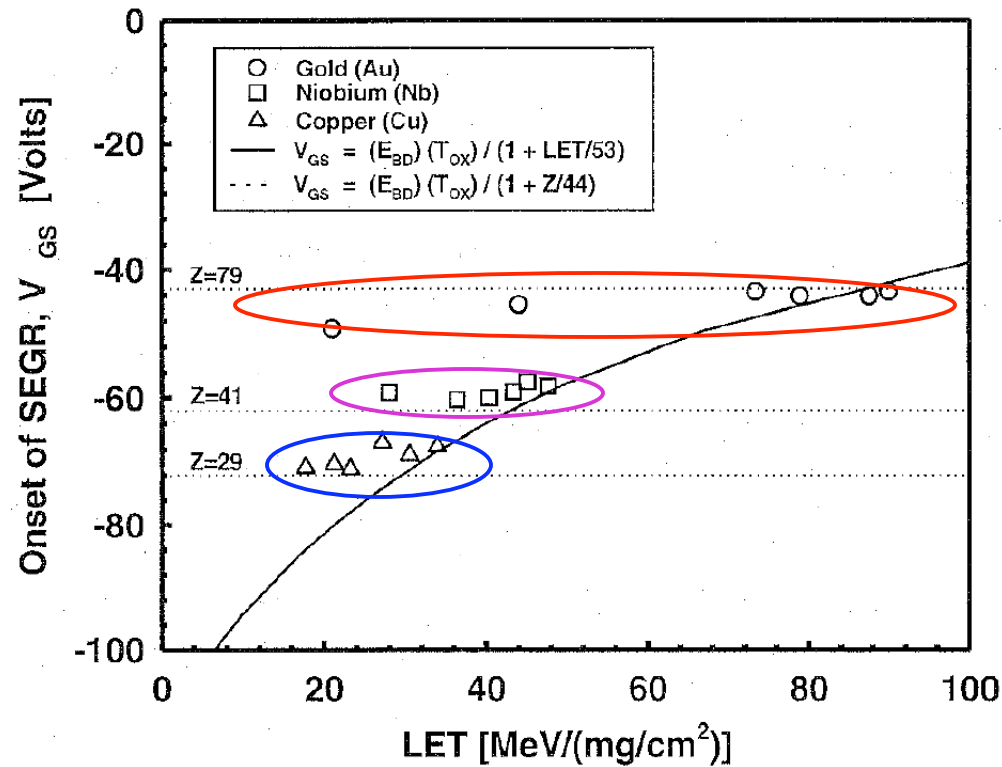
Time for discharge: **~100 fs**

Time for carrier induced melting: **>1000 fs**

Conclusion: Ion strike directly induces a transient "conducting path" in the oxide

Cellere, et al., JAP 99 074101 (2006)

Background: Dependence on Z



Displacement damage effects??

Titus, et al., IEEE TNS 45 2492 (1998)

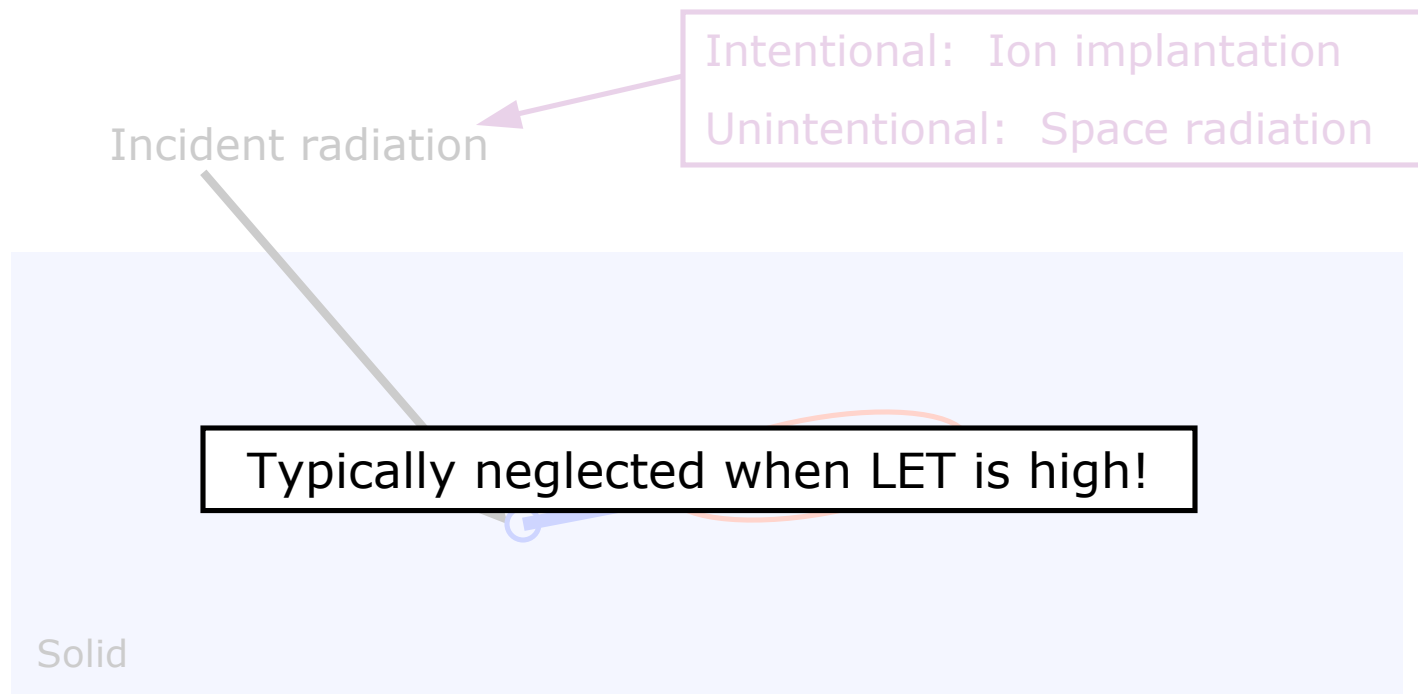
Background: Displacement Damage

Incident Radiation

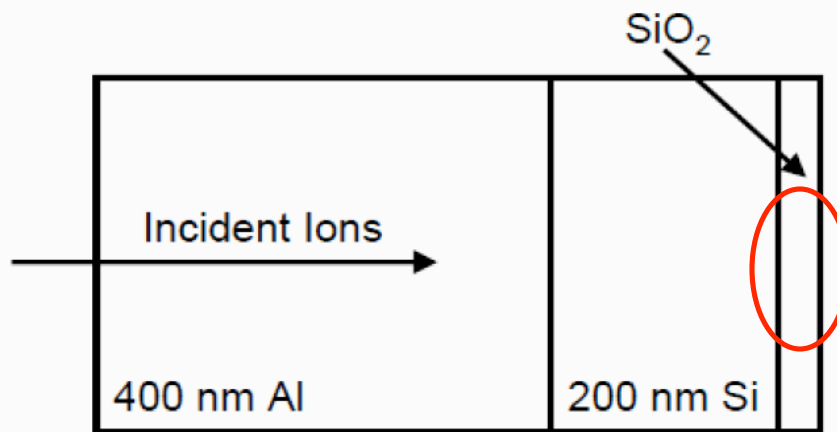
⇒ Atomic recoils/displacements

⇒ Defect/Damage formation

⇒ Altered materials properties!



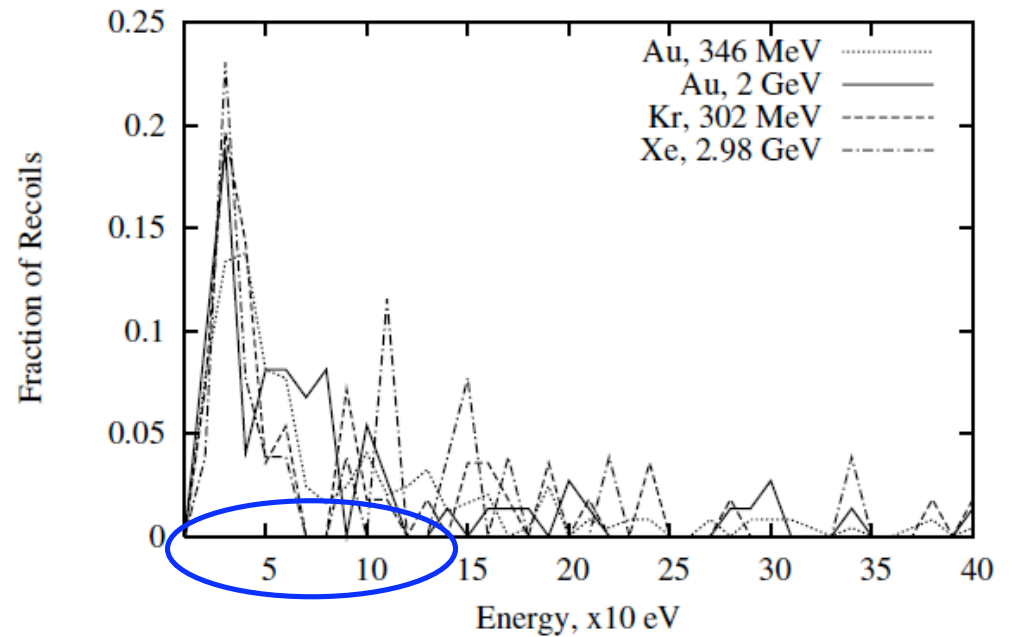
Results: Recoils at High LET



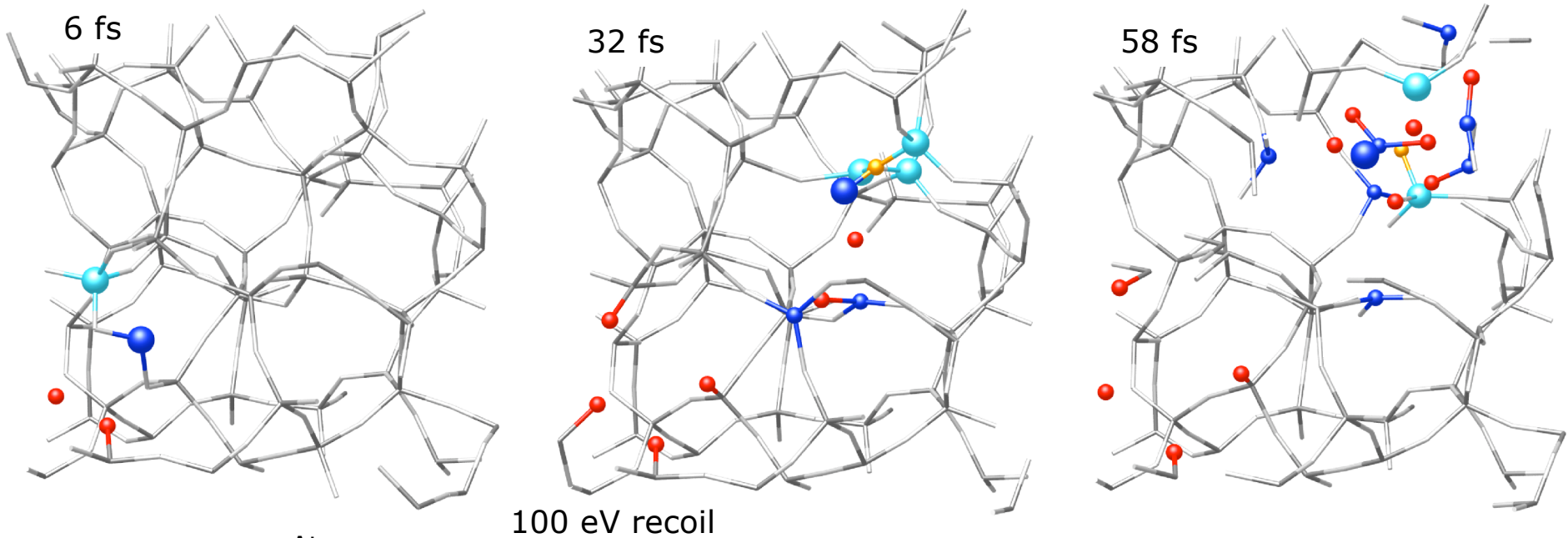
Recoils in oxide layer...

...are principally low-energy recoils!

SRIM: 1-10% of all ions produce a recoil in a 3.3 nm SiO₂ layer!



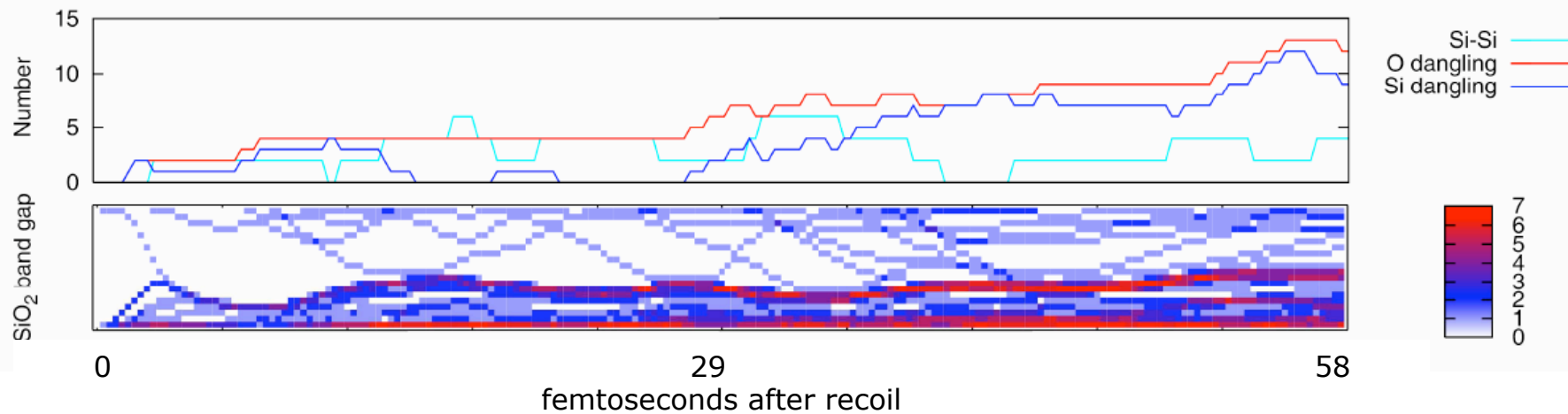
Results: Low-E Recoil Dynamics in SiO₂



Defect	Atom	
	Silicon	Oxygen
Dangling Bond	●	●
Extra Bond	●	●
"Self Bond"	Big Ball	

Damage in amorphous material:
Network defects

Results: Defect States in SiO₂

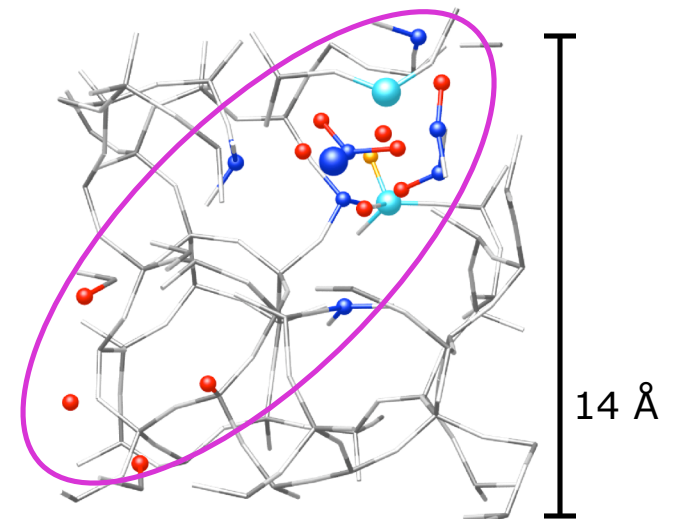


Increasing numbers of defects...

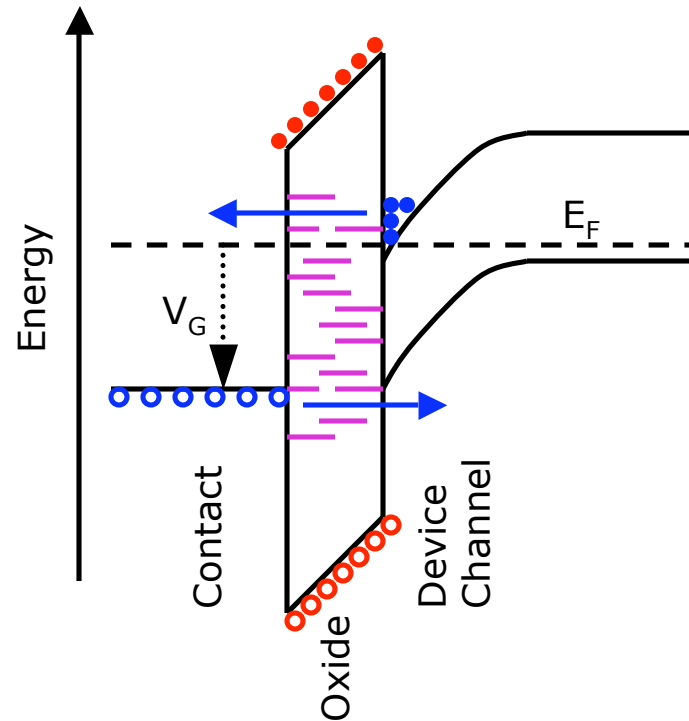
...increasing number of defect states within the bandgap!

Defect states separated by $\sim 2-5 \text{ \AA}$!

Conducting path!



Analysis: Defect-mediated Leakage



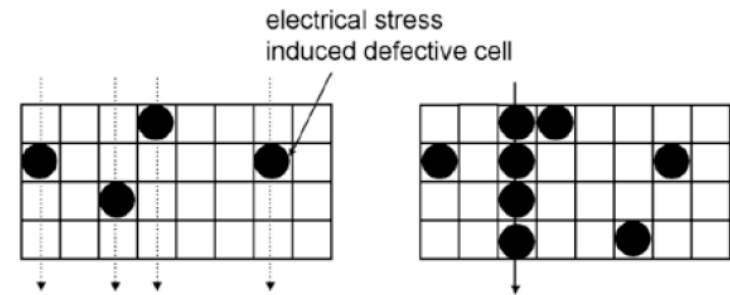
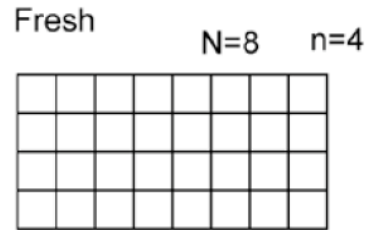
Displacement damage induced defect states
facilitate field-injected leakage

Analysis: Reliability Degradation

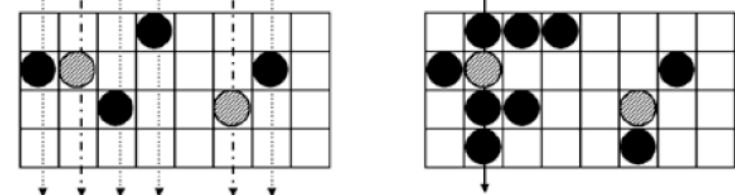
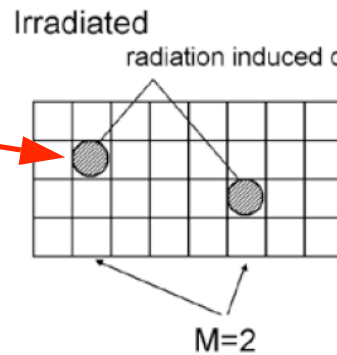
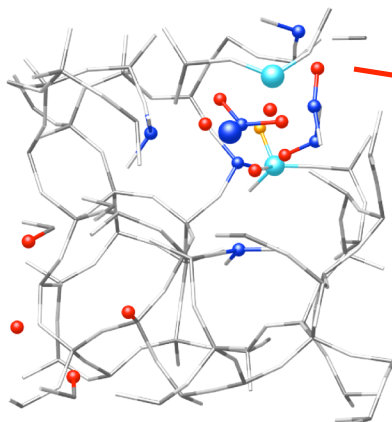
Long-term reliability is degraded by high-LET irradiation...
 ... but *electronic excitation* is transient!

"Percolation Model"

Gate Oxide



Network defects!



Leakage current due to stress

Breakdown

Choi, et al., IEEE TNS v. 39 p. 3045 (2002)

- High-LET irradiations of SiO_2 produce low-energy (<1 keV) atomic recoils
- Low-energy recoils produce network defects in SiO_2
- ...associated with spatially correlated defect states in the SiO_2 band gap
- These defects represent a low-resistivity conducting path
- ...and provide an atomistic explanation for the “percolation model” of high-LET reliability degradation